

Desoldering tips are constructed in the same fashion as regular soldering iron tips. They consist of copper (for heat transfer), iron (for durability) and nickel/chrome finish which makes them visually appealing and defines the area that can wet with solder. In general, they should be maintained similarly as any soldering iron tip. Desoldering tips are hollow through the center of the tip and have a much greater surface area exposed to the environment and the various solder alloys and fluxes in use than soldering tips. It is vitally important to consistently, and correctly, maintain desoldering tips to maximize their performance and life.

Desoldering tips come in two basic varieties; tinnable and non-tinnable. The function of the tip determines if the tip should be tinnable or non-tinnable. For larger ThermoDrive and Flo-D-Sodr style tips, maximum heat transfer and speed of heat delivery is the primary objective. These styles of tips are tinned to improve thermal performance as the melted solder forms an efficient connection between the tip and the work. Precision through-hole and Precision Flo-D-Sodr tips are designed for applications where access may be limited. These tips are not tinned which reduces the chance of contacting adjacent components with molten solder.

For any tinnable style of desoldering tip, the most important step in tip maintenance is to keep the tinnable surface tinned at all times. Whenever the tip is to be used the old tinning layer should be removed using a damp sponge and a fresh coat of solder should be applied immediately to the tinnable surface. Once the desoldering task is completed, the old solder should be removed and the tip should be retinned before the handpiece is placed back in the stand. These steps should be repeated every time the tip is used. Tinnable tips should also be inspected for wear and erosion that will form "holes" in the plating layers over time. These "holes" can be rough and jagged and could cause damage. Any tip that shows significant signs of erosion should be replaced.

For non-tinnable tips, the exterior should be inspected and it should be cleaned using a damp sponge before use. Solder or flux should not be applied to the exterior of the tip at any time.

NEVER use a wire brush or harsh abrasive on the exterior of a desoldering tip as damage could occur to the plated surfaces of the tip which will make the tip fail sooner.

The inside of both tinnable and non-tinnable tips should be inspected periodically and cleaned. When it is determined that the inside of the tip is in need of maintenance (usually clogging or poor solder evacuation), use the PACE Tip Cleaning Kit (p/n 6993-0200-P1) and the appropriate sized tip cleaner. The tip cleaner should fit snugly through the ID (inside diameter) of the tip. Insert the tip cleaner into a **hot tip** and gently ream the ID of the tip while depressing the vacuum button or foot pedal to draw any contaminants into the solder collection cartridge or glass chamber.

If you are having difficulty removing solder and the tip seems to be in good shape, always check your vacuum hoses, in-line filters and solder collection chambers.